

Docket No.: 4425-324



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Wei-Chi LIU et al.

U.S. Patent Application No. 10/697,099

Group Art Unit: 2814

Filed: October 31, 2003

Examiner: NATHAN HA

For: THERMAL DISSIPATING ELEMENT OF A CHIP

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

- ☒ No additional fee is required.
☐ Small entity status of this application has been established.
☐ Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	20	20	0	x \$ 18 =	\$ 0.00
Independent Claims	2	3	0	x \$ 88 =	\$ 0.00
If multiple claims newly presented, add \$290.00					
Fee for extension of time					
TOTAL FEE DUE					\$ 0.00

- ☐ A credit card authorization form in the amount of _____ is attached
- ☒ The Commissioner is hereby authorized to charge payment of any *deficiency* in fees associated with this communication or credit any overpayment, to Deposit Account No. 07-1337, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

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Date: December 9, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/697,099
Applicant : Wei-Chi Liu et al
Filed : October 31, 2003
Title : Thermal Dissipating Element of a Chip
TC/A.U. : 2814
Examiner : HA, NATHAN W
Docket No. : 4425-324

Honorable Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT

Sir:

This paper is in response to the Official Action mailed September 10, 2004. Applicants respectfully request that the Examiner reconsider the amended application according to the following remarks.

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begin on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.